Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and with stand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

Features

- 30V,120A,$R_{DS(on).max}$=3.1mΩ@V_{GS} = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green device available

Applications

- Motor Drives
- UPS
- DC-DC Converter

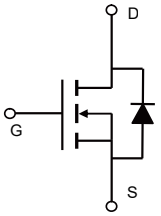
Product Summary

V_{DSS}	30V
$R_{DS(on).max}$@ V_{GS}=10V	3.1mΩ
I_D	120A

Pin Configuration

TO-220F

TO-220C



Schematic

Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	30	V
Continuous drain current (T_C = 25°C)[1]	I_D	120	A
Continuous drain current (T_C = 100°C)[1]		82	A
Pulsed drain current[2]	I_{DM}	480	A
Gate-Source voltage	V_{GSS}	±20	V
Avalanche energy[3]	E_{AS}	540	mJ
Power Dissipation (T_C = 25℃) C C TO-220	P_D	150	W
Power Dissipation (T_C = 25℃) C C TO-220F		52	W
Storage Temperature Range	T_{STG}	-55 to +150	°C
Operating Junction Temperature Range	T_J	-55 to +150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case C C TO-220	$R_{\theta JC}$	0.83	°C/W
Thermal Resistance, Junction-to-Case C C TO-220F		2.4	°C/W
Thermal Resistance, Junction-to-Ambient C C TO-220	$R_{\theta JA}$	62	°C/W
Thermal Resistance, Junction-to-Ambient C C TO-220F		79	°C/W

Package Marking and Ordering Information

Device	Device Package	Marking
VSM120N03-TF	TO-220F	VSM120N03-TF
VSM120N03-TC	TO-220C	VSM120N03-TC

Electrical Characteristics

T_J = 25°C unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV_{DSS}	V_{GS}=0 V, I_D=250uA	30	---	---	V
Gate threshold voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=250uA	1.1	---	2.1	V
Drain-source leakage current	I_{DSS}	V_{DS}=30 V, V_{GS}=0 V, T_J = 25°C	---	---	1	μA
		V_{DS}=30 V, V_{GS}=0 V, T_J = 125°C	---	---	5	μA
Gate leakage current, Forward	I_{GSSF}	V_{GS}=20 V, V_{DS}=0 V	---	---	100	nA
Gate leakage current, Reverse	I_{GSSR}	V_{GS}=-20 V, V_{DS}=0 V	---	---	-100	nA
Drain-source on-state resistance	$R_{DS(on)}$	V_{GS}=10 V, I_D=30 A	---	1.8	3.1	mΩ
		V_{GS}=4.5 V, I_D=15 A		2.4	4.5	mΩ
Forward transconductance	g_{fs}	V_{DS} =5 V , I_D=50A	26	---	---	S
Dynamic characteristics						
Input capacitance	C_{iss}	V_{DS} = 20 V, V_{GS} = 0 V, F = 1MHz	---	8430	---	pF
Output capacitance	C_{oss}		---	930	---	
Reverse transfer capacitance	C_{rss}		---	879	---	
Turn-on delay time	$t_{d(on)}$	V_{DD} = 30V,V_{GS}=10V, I_D =20 A	---	15	---	ns
Rise time	t_r		---	17	---	
Turn-off delay time	$t_{d(off)}$		---	52	---	
Fall time	t_f		---	23	---	
Gate resistance	R_g	V_{GS}=0V, V_{DS}=0V, F=1MHz	---	1.67	---	Ω
Gate charge characteristics						
Gate to source charge	Q_{gs}	V_{DS}=20 V, I_D=20A, V_{GS}=10 V	---	23	---	nC
Gate to drain charge	Q_{gd}		---	25	---	
Gate charge total	Q_g		---	146	---	
Drain-Source diode characteristics and Maximum Ratings						
Continuous Source Current	I_S		---	---	120	A
Pulsed Source Current[4)]	I_{SM}		---	---	480	A
Diode Forward Voltage	V_{SD}	V_{GS}=0V, I_S=50A, T_J=25℃	---	---	1.2	V
Reverse Recovery Time	t_{rr}	I_S=20A, di/dt=60A/us, T_J=25℃	---	117	---	ns
Reverse Recovery Charge	Q_{rr}		---	30	---	nC

Notes:

1: The maximum junction current rating is package limited.

2: Repetitive Rating: Pulse width limited by maximum junction temperature.

3: V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=104A, R_G=25Ω, Starting T_J=25℃.

4: Pulse Test：Pulse Width ≤300 μ s, Duty Cycle≤2%.

Electrical Characteristics Diagrams

Figure 1. Typ. Output Characteristics

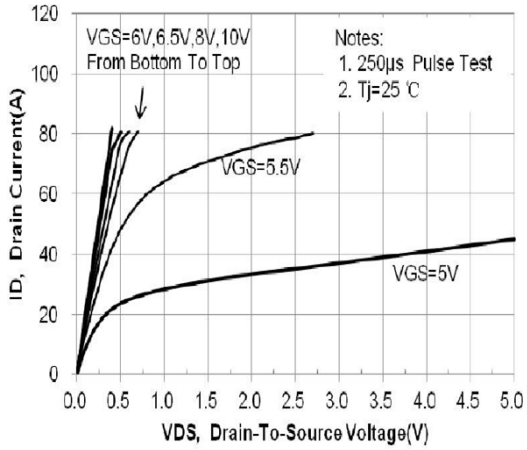


Figure 2. Transfer Characteristics

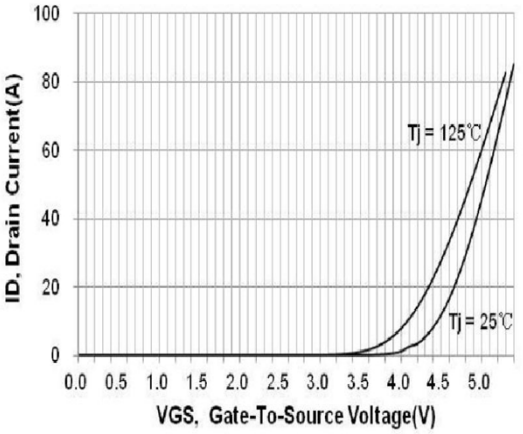


Figure 3. Capacitance Characteristics

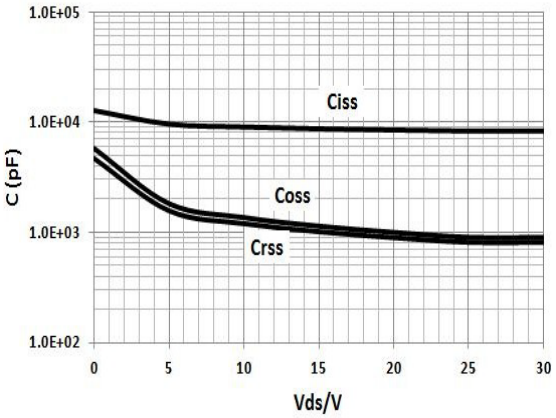


Figure 4. Gate Charge Waveform

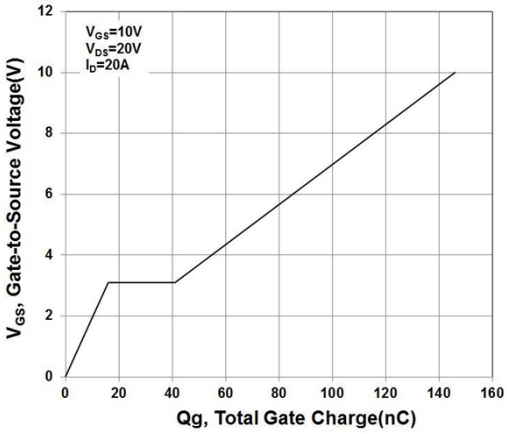


Figure 5. Body-Diode Characteristics

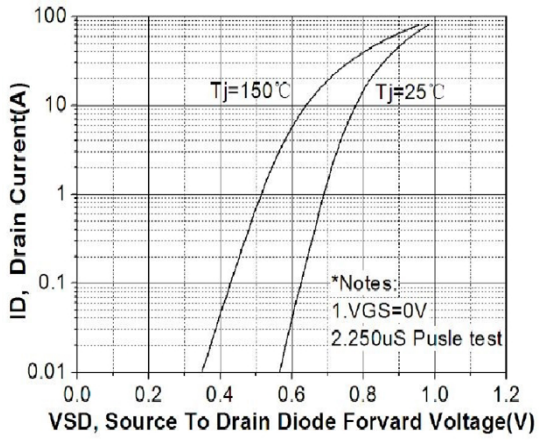


Figure 6.Maximum Safe Operating Area

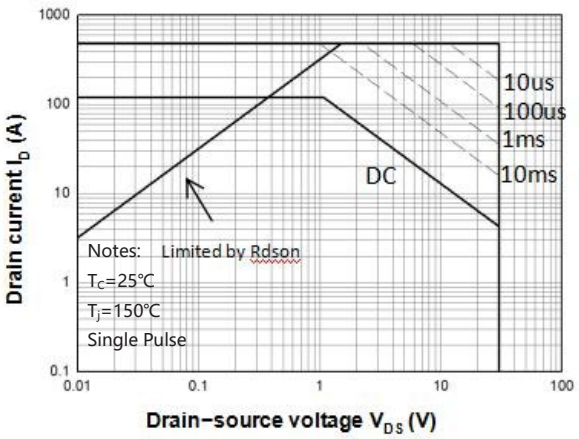


Figure 6. Normalized Maximum Transient Thermal Impedance (RthJC)

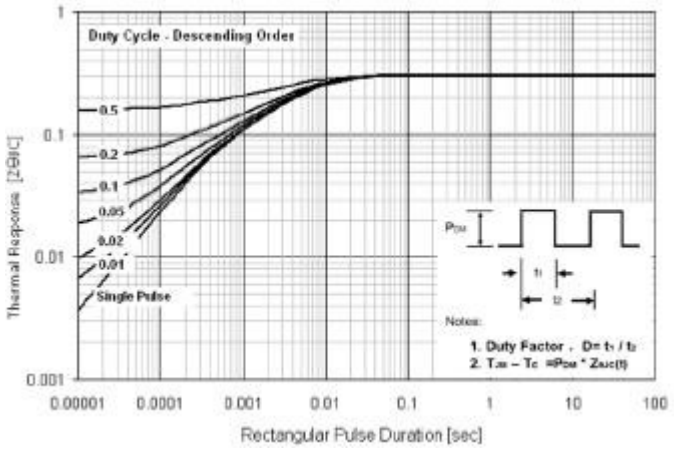
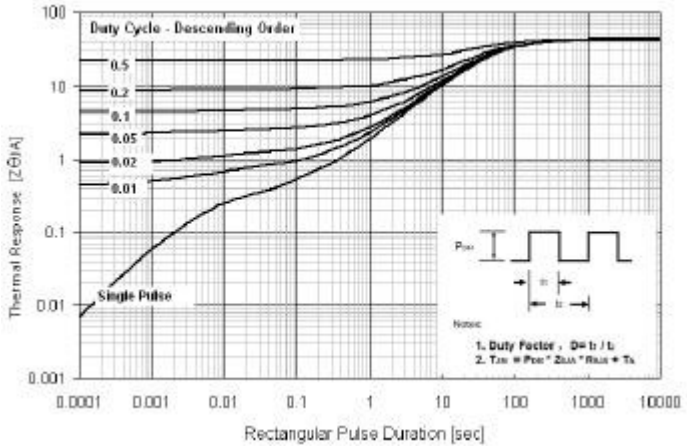


Figure 7. Normalized Maximum Transient Thermal Impedance (RthJA)



Test Circuit & Waveform

Figure 8. Gate Charge Test Circuit & Waveform

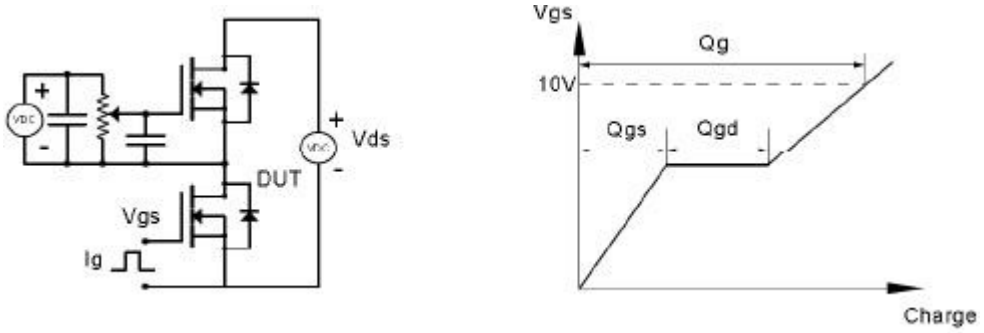


Figure 9. Resistive Switching Test Circuit & Waveforms

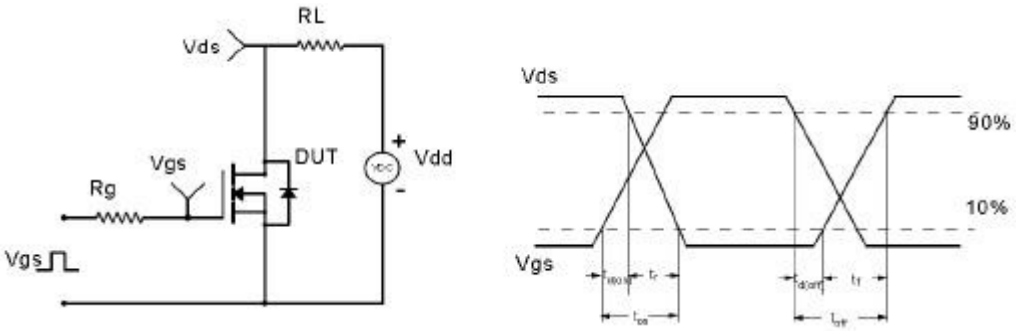


Figure 10. Unclamped Inductive Switching (UIS) Test Circuit & Waveform

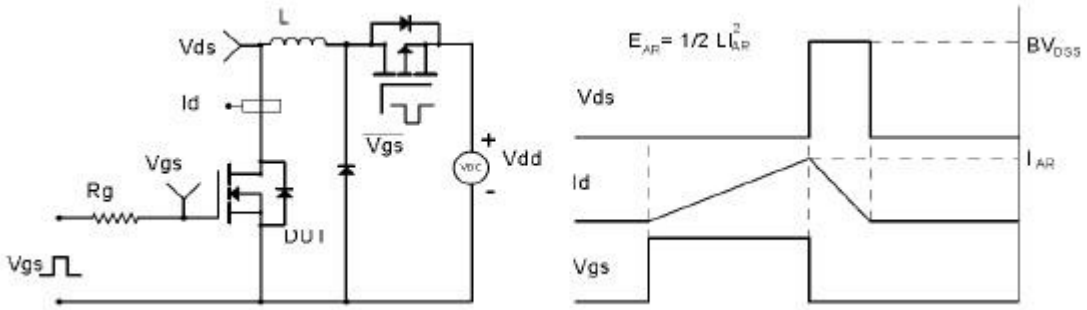


Figure 11. Diode Recovery Circuit & Waveform